


# MATERIAL DECLARATION SHEET



Material Number	SMAJ Series			
Product Line	ESD Protection Products			
Compliance Date	1 Jan 2005			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Dice	Silicon with metal	0.00192	Silicon	7440-21-3	98	2.94	3
				Nickel	7440-02-0	1.1	0.033	
2	High-melting point Solder paste	Tin-Lead solder	0.00256	Lead	7439-92-1	93.5	3.74	4
				Tin	7440-31-5	0.05	0.2	
				Silver	7440-22-4	1.5	0.06	
3	Lead frame & clip	Copper alloy	0.0266	Copper	7440-50-8	97.73	40.62	41.56
				Iron	7439-89-6	2.13	0.8853	
4	Mould compound	Epoxy material	0.0322	Silica(SiO <sub>2</sub> )	7631-86-9	70	35.22	50.31
				Epoxy resin	68928-70-1	19.99	10.06	
				Antimony Trioxide	1309-64-4	4.99	2.515	
				Phenolic resin	29690-82-2	4.99	2.515	
5	Plating	Tin solder	0.00064	Tin	7440-31-5	100	1	1
		Total weight	0.06400					

**This Document was updated on:** 26 January 2010

**Important remarks:**

1. It is the responsibility of the user to verify they are accessing the latest version.
2. RoHS exemption – 7a high temperature solder